

Material Composition Data



Product: GSX-533

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GSX-533 - SM Crystal for Bluetooth / Wireless

Sub-Assembly	Material	Substance	CAS No	Mass (mg)	Sub-Assembly % by mass
BASE	Ceramics	Al ₂ O ₃	1344-28-1	24.550	77.16
	Ceramics	CaO	1305-78-8	0.175	0.55
	Ceramics	Co	7440-48-4	0.315	0.99
	Ceramics	Cr ₂ O ₃ (Non hex)	1308-38-9	0.184	0.58
	Ceramics	MgO	1309-48-4	0.162	0.51
	Ceramics	Mo	7439-98-7	0.363	1.14
	Ceramics	SiO ₂	14808-60-7	1.199	3.77
	Metallisation	W	7440-33-7	3.539	11.12
	Plating	Au	7440-57-5	0.073	0.23
	Plating	Ni	7440-02-0	1.256	3.95
Blank	quartz	SiO ₂	14808-60-7	1.107	100.00
LID	Kovar (AgCu clad lid)	Ag	7440-22-4	1.266	13.15
	Kovar (AgCu clad lid)	C	7440-44-0	0.001	0.01
	Kovar (AgCu clad lid)	Co	7440-48-4	1.196	12.43
	Kovar (AgCu clad lid)	Cu	7440-50-8	0.493	5.12
	Kovar (AgCu clad lid)	Fe	7439-89-6	3.786	39.34
	Kovar (AgCu clad lid)	Mn	7439-96-5	0.025	0.26
	Kovar (AgCu clad lid)	Ni	7440-02-0	2.827	29.37
	Kovar (AgCu clad lid)	Si	7440-21-3	0.006	0.06
	Others	Hydrocarbonic Solvent	64742-94-5	0.006	0.06
	Others	Silicon Resin	7631-86-9	0.018	0.19
electrode	GOLD TECH	Au	7440-57-5	0.099	56.90
	SOLAR	Cr	7440-47-3	0.001	0.57
	silver powder	As	7440-38-2	0.074	42.53
Total Mass:				42.721 mg	

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